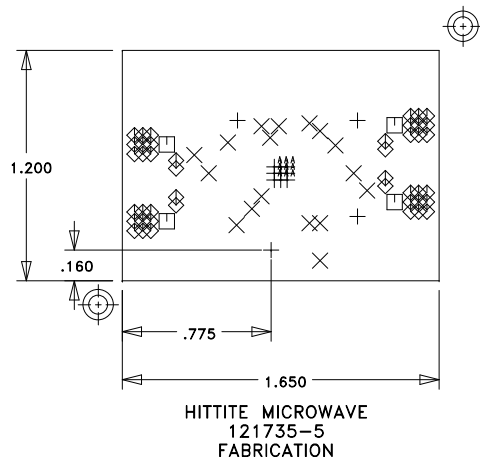


DO NOT SCALE PRINT

	SILKSCREEN
	SOLDERMASK
.062/.067	METAL-01 1/2oz Cu .028 ± 0.002 FR4 (CRITICAL)
	METAL-02 1/2oz Cu Prepreg as Required
	METAL-03 1/2 oz Cu FR4 as Required
	METAL-04 1/2 oz Cu



SIZE	QTY	SYM	PLATED	TOL
10	9	+	YES	+/-3
14	17	X	YES	+/-3
18	44	◇	YES	+/-3
43	4	+	YES	+/-3
80	4	□	YES	+/-3

PROPRIETARY TO HITTITE MICROWAVE CORPORATION

UNLESS OTHERWISE SPECIFIED:	DWN BY:
DIMENSIONS ARE IN INCHES (MM)	MARTIN LYONS
DRAWING PRACTICES PER MIL-STD-100	ENGINEER:
	A. CELEBI/FATIH GOLCUK
TOLERANCES:	
.XX	+/- 0.010
.XXX	+/- 0.005
.XXXX	+/- 0.002
ANGLES	+/- .5 DEG

DWN BY:	MARTIN LYONS
ENGINEER:	A. CELEBI/FATIH GOLCUK



HITTITE MICROWAVE CORPORATION
20 Alpha Road Chelmsford, MA 01824

TITLE
PCB, EVAL 75 OHM
HMC770LP4B

SIZE	CODE ID NO.	DRAWING NO.	REV
A	1CN88	121735	5
SCALE:	WT	SHEET 1 of 1	

NOTES:

MATERIALS AND TOLERANCES:

- MATERIAL: DOUBLE SIDED FR4, HALF OUNCE COPPER BOTH SIDES.
- FINISH: GOLD PLATE PER ASTM B-488 TYPE III CODE A 8-40 MICROINCHES OVER NICKEL PER QQ-N-290 100 MICROINCHES MINIMUM.
- APPLY LPI SOLDERMASK TOP SIDE ONLY. COLOR: GREEN.
- SILKSCREEN TOP SIDE WITH WHITE NON-CONDUCTIVE INK. ENSURE SILKSCREEN DOES NOT COVER COMPONENT PADS - CLIP SILKSCREEN IF NECESSARY.
- MANUFACTURE PER IPC-6012 CLASS 2.
- ALL HOLES TO BE LOCATED WITHIN ± 0.003 " OF CENTER OF PAD OR OTHER TRUE POSITION.
- COPPER PLATE ALL HOLES MINIMUM .001" COPPER WALL THICKNESS.
- "SIZE" IN DRILL LEGEND IS IN MILS AND REFERS TO FINISHED HOLE SIZE.
- WARPAGE: $< .010$ " PER LINEAR INCH.
- FRONT TO BACK REGISTRATION: ± 0.003 " MAX.
- REMOVE METAL BURRS FROM EDGE OF PCB AFTER PANEL SEPARATION.

SPECIAL REQUIREMENTS:

- CRITICAL LINE WIDTH OF .020" ± 0.001 " ON METAL-01.

VENDOR NOTES:

- VENDOR SHALL NOT ADD NAME, LOGO, DATE CODE, UL LISTING OR ANY OTHER MARKING TO ANY VISIBLE LAYER.
- ANY CHANGES TO METAL LAYERS OR STACKUP MUST BE APPROVED BY HITTITE MICROWAVE.
- BOARDS MUST PASS VISUAL INSPECTION PER IPC-A-600 CLASS 2.